

LMH0046 HD/SD SDI Reclocker With Dual Differential Outputs

Check for Samples: LMH0046

FEATURES

- Supports SMPTE 292M and SMPTE 259M (A & C) Serial Digital Video Standards
- Supports 143 Mbps, 270 Mbps, 1.483 Gbps, and 1.485 Gbps Serial Data Rate Operation
- Supports DVB-ASI at 270 Mbps
- Single 3.3V Supply Operation
- 330 mW Typical Power Consumption
- · Two Differential, Reclocked Outputs
- Choice of Second Reclocked Output or Low-Jitter, Differential, Data-Rate Clock Output
- Single 27 MHz External Crystal or Reference Clock Input
- Manual Rate Select Input
- SD/HD Operating Rate Indicator Output
- Lock Detect Indicator Output
- Output Mute Function for Data and Clock
- Auto/Manual Reclocker Bypass
- Differential LVPECL Compatible Serial Data Inputs and Outputs
- LVCMOS Control Inputs and Indicator Outputs
- 20-Pin HTSSOP Package
- Industrial Temperature Range: -40°C to +85°C

APPLICATIONS

- SDTV/HDTV Serial Digital Video Interfaces For:
 - Digital Video Routers and Switchers
 - Digital Video Processing and Editing Equipment
 - DVB-ASI Equipment
 - Video Standards and Format Converters

DESCRIPTION

The LMH0046 HD/SD SDI Reclocker retimes serial digital video data conforming to the SMPTE 292M and SMPTE 259M (A & C) standards. The LMH0046 operates at serial data rates of 143 Mbps, 270 Mbps, 1.483 Gbps and 1.485 Gbps. The LMH0046 supports DVB-ASI operation at 270 Mbps.

The LMH0046 automatically detects the incoming data rate and adjusts itself to retime the incoming data to suppress accumulated jitter. The LMH0046 recovers the serial data-rate clock and optionally provides it as an output. The LMH0046 has two differential serial data outputs; the second output may be selected as a low-jitter, data-rate clock output. Controls and indicators are: serial clock or second serial data output select, manual rate select input, SD/HD rate indicator output, lock detect output, auto/manual data bypass and output mute. The serial data inputs, outputs, and serial data-rate clock outputs are differential LVPECL compatible. The CML serial data and serial data-rate clock outputs are suitable for driving 100Ω differentially terminated networks. The control logic inputs and outputs are LVCMOS compatible.

The LMH0046 is powered from a single 3.3V supply. Power dissipation is typically 330 mW. The device is housed in a 20-pin HTSSOP package.

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Typical Application

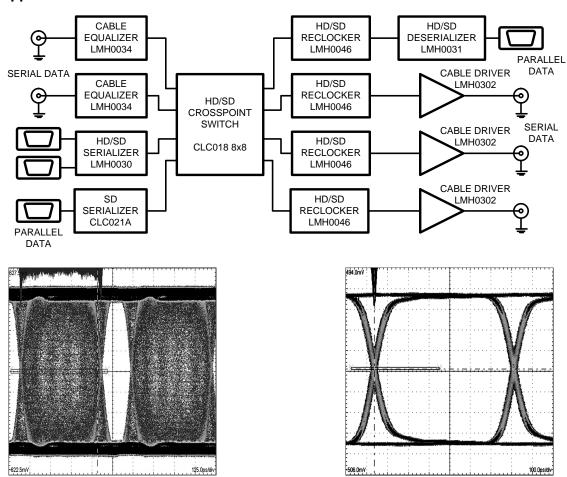
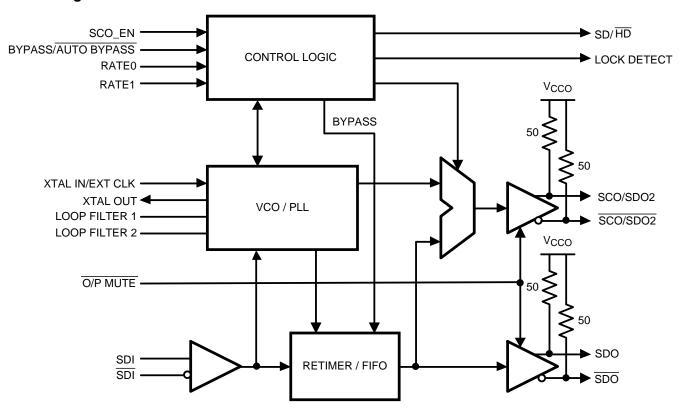


Figure 1. 1.485 Gbps Signal Before Reclocking (0.75 UI Jitter)

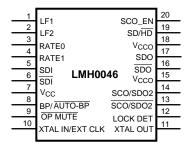
Figure 2. 1.485 Gbps Signal After Reclocking (0.05 UI Jitter)



Block Diagram



Connection Diagram



The exposed die attach pad is the negative electrical terminal for this device. It must be connected to the negative power supply voltage.

Figure 3. 20-Pin HTSSOP See PWP0020A Package



Table 1. PIN DESCRIPTIONS

Pin	Name	Description
1	LF1	Loop Filter
2	LF2	Loop Filter
3	RATE 0	Data Rate Select Input
4	RATE 1	Data Rate Select Input
5	SDI	Data Input True
6	SDI	Data Input Complement
7	V _{CC}	Positive power supply input
8	BYPASS/AUTO BYPASS	Bypass/Auto Bypass mode select
9	OUTPUT MUTE	Data and Clock Output Mute Input (active low)
10	XTAL IN/EXT CLK	Crystal or External Oscillator Input
11	XTAL OUT	Crystal Oscillator Output
12	LOCK DETECT	PLL Lock Detect Output (active high)
13	SCO/SDO2	Serial Clock or Serial Data Output 2 Complement
14	SCO/SDO2	Serial Clock or Serial Data Output 2 True
15	V _{CCO}	Positive power supply input (Output Driver)
16	SDO	Data Output Complement
17	SDO	Data Output True
18	V _{CCO}	Positive power supply input (Output Driver)
19	SD/HD	Data Rate Range Output
20	SCO_EN	Serial Clock or Serial Data 2 Output select (active high enables serial clock output)
DAP	V _{EE}	Connect exposed DAP to negative power supply (ground)

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

Supply Voltage (V _{CC} -V _{EE})		4.0V
Logic Supply Voltage (Vi)		V _{EE} -0.15V to V _{CC} +0.15V
Logic Input Current (single input):	Vi = V _{EE} −0.15V	−5 mA
	Vi = V _{CC} +0.15V	+5 mA
Logic Output Voltage (Vo)	V _{EE} -0.15V to V _{CC} +0.15V	
Logic Output Source/Sink Current	±8 mA	
Serial Data Input Voltage (V _{SDI})	V _{CC} to V _{CC} -2.0V	
Serial Data Output Sink Current (I _{SDO})	24 mA	
Package Thermal Resistance, HTSSOP	θ_{JA}	26.6°C/W
	θ_{JC}	2.4°C/W
Storage Temp. Range		−65°C to +150°C
Junction Temperature		+150°C
Lead Temperature (Soldering 4 Sec)	+260°C (Pb-free)	
ESD Rating (HBM)	7 kV	
ESD Rating (MM)	350V	
ESD Rating (CDM)		1250V

^{(1) &}quot;Absolute Maximum Ratings" are those parameter values beyond which the life and operation of the device cannot be ensured. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. The table of "Electrical Characteristics" specifies acceptable device operating conditions.

Recommended Operating Conditions

Supply Voltage (V _{CC} –V _{EE})	3.3V ±5%
Logic Input Voltage	V _{EE} to V _{CC}
Differential Serial Input Voltage	800 mV ±10%
Serial Data or Clock Output Sink	
Current (I _{SO})	16 mA max.
Operating Free Air Temperature (T _A)	-40°C to +85°C

⁽²⁾ It is anticipated that this device will not be offered in a military qualified version. If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.



DC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)(2)

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
V_{IH}	Input Voltage High Level		Logic inputs	2		V_{CC}	V
V_{IL}	Input Voltage Low Level			V _{EE}		8.0	V
I _{IH}	Input Current High Level	$V_{IH} = V_{CC}$			1	65	μA
I _{IL}	Input Current Low Level	$V_{IL} = V_{EE}$			-1	-25	μA
V_{OH}	Output Voltage High Level	I _{OH} = −2 mA	Logic outputs	2			V
V_{OL}	Output Voltage Low Level	I_{OL} = +2 mA				V _{EE} + 0.6	V
V_{SDID}	Serial Input Voltage, Differential		SDI	200		1600	mV_{P-P}
V_{CMI}	Input Common Mode Voltage			V _{CC} -1.6		V _{CC} -0.2	V
V_{SDOD}	Serial Output Voltage, Differential	100Ω differential load	SDO, SCO	720	800	880	mV_{P-P}
V _{CMO}	Output Common Mode Voltage	100Ω differential load			V _{CC} - V _{SDOD}		V
I _{CC}	Power Supply Current, 3.3V supply, Total	1485 Mbps, NTSC color bar pattern			100		mA

Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are referenced to V_{EE} (equal to zero volts).

AC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
BR _{SD}	Serial Data Rate	SMPTE 259M, A	SDI, SDO		143		Mbps
BR _{SD}	Serial Data Rate	SMPTE 259M, C			270		Mbps
BR _{SD}	Serial Data Rate	SMPTE 292M			1483, 1485		Mbps
TOL _{JIT}	Serial Input Jitter Tolerance	143 or 270 Mbps ⁽²⁾⁽³⁾⁽⁴⁾	SDI		>6		UI _{P-P}
TOL _{JIT}	Serial Input Jitter Tolerance	143 or 270 Mbps ⁽²⁾⁽⁵⁾⁽⁶⁾		>0.6			UI _{P-P}
TOL _{JIT}	Serial Input Jitter Tolerance	1483 or 1485 Mbps ⁽²⁾⁽⁵⁾ (3)		>6			UI _{P-P}
TOL _{JIT}	Serial Input Jitter Tolerance	1483 or 1485 Mbps ⁽²⁾⁽⁵⁾⁽⁶⁾		>0.6			UI _{P-P}
t _{JIT}	Serial Data Output Jitter	143 Mbps ⁽⁵⁾⁽⁷⁾	SDO		0.02	0.08	UI_P-P
t _{JIT}	Serial Data Output Jitter	270 Mbps ⁽⁵⁾⁽⁷⁾			0.02	0.08	UI _{P-P}
t _{JIT}	Serial Data Output Jitter	1483 or 1485 Mbps ⁽⁵⁾⁽⁷⁾			0.05	0.1	UI _{P-P}
BW _{LOOP}	Loop Bandwidth	270 Mbps, <0.1dB Peaking			300		kHz
		1485 Mbps, <0.1dB Peaking			2.0		MHz

Typical values are stated for: $V_{CC} = +3.3V$, $T_A = +25$ °C.

Typical values are stated for: V_{CC} = +3.3V, T_A = +25°C. Peak-to-peak amplitude with sinusoidal modulation per SMPTE RP 184-1996 paragraph 4.1. The test data signal shall be color bars.

Refer to "A1" in Figure 1 of SMPTE RP 184-1996.

Characterized to the limitations of SDI test equipment.

This parameter is ensured by characterization over voltage and temperature limits.

Refer to "A2" in Figure 1 of SMPTE RP 184-1996.

Serial Data Output Jitter is total output jitter with 0.2 UI_{P-P} input jitter.



AC Electrical Characteristics (continued)

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)

Symbol Parameter		Conditions	Reference	Min	Тур	Max	Units	
F _{co}	Serial Clock Output Frequency	143 Mbps data rate	SCO		143		MHz	
F _{CO} Serial Clock Output Frequency		270 Mbps data rate			270		MHz	
F _{CO}	Serial Clock Output Frequency	1483 Mbps data rate			1483		MHz	
F _{CO}	Serial Clock Output Frequency	1485 Mbps data rate	7		1485		MHz	
t _{JIT}	Serial Clock Output Jitter				2	3	ps _{RMS}	
	Serial Clock Output Alignment with respect to Data Interval		SDO, SCO	40		60	%	
	Serial Clock Output Duty Cycle		SCO	45		55	%	
T _{ACQ}	Acquisition Time	Auto-Rate Detect Mode (8) (9)			10	16	ms	
		Fixed Rate Mode (8) (9)			1	6	ms	
t _r , t _f	Input rise/fall time	10%–90%	Logic inputs		1.5	3	ns	
t _r , t _f	Input rise/fall time	20%-80%, 143 or 270 Mbps	SDI			1500	ps	
t _r , t _f	Input rise/fall time	20%–80%, 1483 or 1485 Mbps				270	ps	
t _r , t _f Output rise/fall time		10%–90%	Logic outputs		1.5	3	ns	
t _r , t _f	Output rise/fall time	20%-80% ⁽¹⁰⁾	SDO, SCO		90	130	ps	
F _{REF}	Reference Clock Frequency				27		MHz	
F _{TOL}	Reference Clock Frequency Tolerance				±50		ppm	

⁽⁸⁾ Spec is ensured by design. (9) Measured from first SDI transition until Lock Detect (LD) output goes high (true). (10) $R_L = 100\Omega$ differential.



DEVICE DESCRIPTION

The LMH0046 HD/SD SDI Reclocker is used in many types of digital video signal processing equipment. Supported serial digital video standards are SMPTE 259M (A & C) and SMPTE 292M. Corresponding serial data rates are 143 Mbps, 270 Mbps, 1.483 Gbps and 1.485 Gbps. DVB-ASI data at 270 Mbps may also be retimed. The LMH0046 retimes the serial data stream to suppress accumulated jitter. It provides two low-jitter, differential, serial data outputs. The second output may be selected to output either serial data or a low-jitter serial data-rate clock. Controls and indicators are: serial data-rate clock or second serial data output select, manual rate select input, SD/HD rate output, lock detect output, auto/manual data bypass and output mute.

Serial data inputs are CML and LVPECL compatible. Serial data and data-rate clock outputs are differential CML and produce LVPECL compatible levels. The output buffer design can drive AC or DC-coupled, terminated 100Ω differential loads. The differential output level is 800 mV_{P-P} ±10% into 100Ω AC or DC-coupled differential loads. Logic inputs and outputs are LVCMOS compatible.

The device package is a 20-pin HTSSOP with an exposed die attach pad. The exposed die attach pad is electrically connected to device ground (V_{EE}) and is the negative electrical terminal for the device. This terminal must be connected to the negative power supply or circuit ground.

Serial Data Inputs, Serial Data and Clock Outputs

SERIAL DATA INPUT AND OUTPUTS

The differential serial data input, SDI, accepts serial digital video data at the rates specified in Table 2. The serial data input is differential LVPECL compatible. The input is intended to be DC interfaced to devices such as the LMH0034 adaptive cable equalizer. The input is not internally terminated or biased. The input may be AC-coupled if a suitable input bias voltage is provided. Figure 4 shows the equivalent input circuit for SDI and SDI.

The LMH0046 has two, retimed, differential, serial data outputs, SDO and SCO/SDO2. These outputs provide low jitter, differential, retimed data to devices such as the LMH0002 cable driver or the LMH0031 deserializer. Output SCO/SDO2 is multiplexed and can provide either a second serial data output or a serial data-rate clock output. Figure 5 shows the equivalent output circuit for SDO, SDI, SCO/SDO2, and SCO/SDO2.

The SCO_EN input controls the operating mode for the SCO/SDO2 output. When the SCO_EN input is high the SCO/SDO2 output provides a serial data-rate clock. When SCO_EN is low, the SCO/SDO2 output provides retimed serial data.

Both differential serial data outputs, SDO and SCO/SDO2, are muted when the $\overline{\text{MUTE}}$ input is a logic low level. SCO/SDO2 also mutes when the Bypass mode is activated when this output is operating as the serial clock output. When muted, SDO and $\overline{\text{SDO}}$ (or SDO2 and $\overline{\text{SDO2}}$) will assume opposite differential output levels. The CML serial data outputs are differential LVPECL compatible. These outputs have internal 50 Ω pull-ups and are suitable for driving AC or DC-coupled, 100Ω center-tapped, AC grounded or 100Ω un-center-tapped, differentially terminated networks.



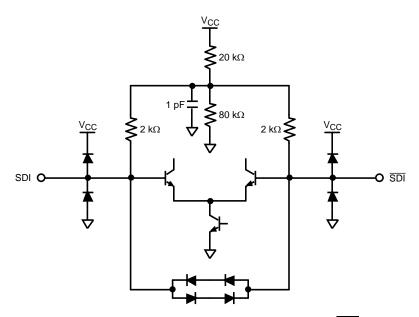


Figure 4. Equivalent SDI Input Circuit (SDI, SDI)

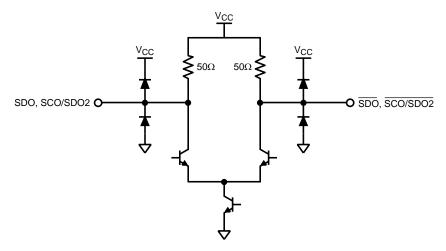


Figure 5. Equivalent SDO Output Circuit (SDO, SDO, SCO/SDO2, SCO/SDO2)

OPERATING SERIAL DATA RATES

This device operates at serial data rates of 143 Mbps, 270 Mbps, 1483 Mbps and 1485 Mbps. The device does not lock to harmonics of these rates. The device does not lock and automatically enters the reclocker bypass mode for the following data rates: 177 Mbps, 360 Mbps, and 540 Mbps.

SERIAL DATA CLOCK/SERIAL DATA 2 OUTPUT

The Serial Data Clock/Serial Data 2 Output is controlled by the SCO_EN input and provides either a second retimed serial data output or a low jitter differential clock output appropriate to the serial data rate being processed. When operating as a serial clock output, the rising edge of the clock will be positioned within the corresponding serial data bit interval within 10% of the center of the data interval.

Differential output SCO/SDO2 functions as the second serial data output when the SCO_EN input is a logic-low level. This output functions as the serial data-rate clock output when the SCO_EN input is a logic-high level. The SCO_EN input has an internal pull-down device and the default state of SCO_EN is low (serial data output 2 enabled). SCO/SDO2 is muted when the MUTE input is a logic low level. When the Bypass mode is activated and this output is functioning as a serial clock output, the output will also be muted.

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Control Inputs and Indicator Outputs

SERIAL DATA RATE SELECTOR

The Serial Data Rate Selector (RATE [1:0]) permits the user to fix the operating serial data rate. The pins have internal pull-downs which maintain a logic-low input condition unless externally driven to a logic-high condition. This input also serves to place the device in a test mode. The codes shown in Table 2 select the desired operating serial data rate. The LMH0046 then enters either the Auto-Rate Detect mode or a single operating rate. Selecting the 270 Mbps rate mode may also be used when reclocking DVB-ASI data. DVB-ASI data is MPEG2 coded data that is transmitted in 8B10B coding. The device will reclock this data without harmonic locking. Auto-Rate Detect mode may be used for any supported data rate, including DVB-ASI.

Table 2. Data Rate Select Input Codes

Rate [1:0] Code	Data Rate or Mode	Comments
00	Auto-Rate Detect mode	143 Mbps rate operation supported only in ARD mode
01	270 Mbps	May be used to support DVB-ASI operation
10	1483/1485 Mbps	

LOCK DETECT

The Lock Detect (<u>LD</u>) output, when high, indicates that data is being received and the PLL is locked. LD may be connected to the MUTE input to mute the data and clock outputs when no data signal is being received. See Table 3.

MUTE

The MUTE input, when low, mutes the serial data <u>and clock</u> outputs. It may be connected to Lock Detect or externally driven to mute or un-mute the outputs. If MUTE is connected to LD, then the data and <u>clock</u> outputs are muted when the PLL is not locked. This function overrides the Bypass function: see <u>Table 3</u>. MUTE has an internal pull-up device to enable the output by default.

BYPASS/AUTO BYPASS

The Bypass/Auto Bypass input, when high, forces the device to output the data without reclocking it. When this input is low, the device automatically bypasses the reclocking function when the device is in an unlocked condition or the detected data rate is a rate which the device does not support. See Table 3. BYPASS/AUTO BYPASS has an internal pull-down device.

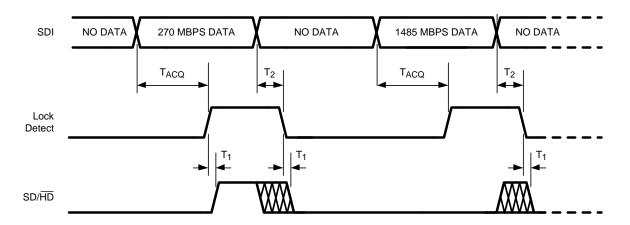
Table 3. Control Functionality

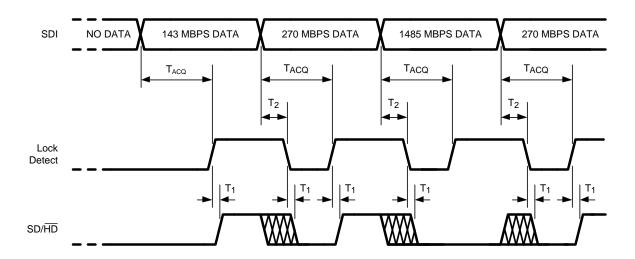
LOCK DETECT	OUTPUT MUTE	BYPASS/AUTO BYPASS	DEVICE STATUS
0	1	0	PLL unlocked, reclocker bypassed
1	1	0	PLL locked to supported data rate, reclocker not bypassed
X	0	X	Outputs muted
0	LOCK DETECT	Χ	Outputs muted
1	LOCK DETECT	0	PLL locked to supported data rate, reclocker not bypassed
1	LOCK DETECT	1	PLL locked to supported data rate, reclocker bypassed
X	1	1	Outputs not muted, reclocker bypassed

SD/HD

The SD/HD output indicates whether the LMH0046 is processing SD or HD data rates. It may be used to control another device such as the LMH0002 cable driver. When this output is high it indicates that the data rate is 270 Mbps (or 143 Mbps). When low, the indicated data rate is 1483 or 1485 Mbps. The SD/HD output is a registered function and is only valid when the PLL is locked and the Lock Detect output is high. When the PLL is not locked (the Lock Detect output is low), the SD/HD output defaults to HD (low). The SD/HD output is undefined for a short time after lock detect assertion or de-assertion due to a data rate change on SDI. See Figure 6 for a timing diagram showing the relationship between SDI, Lock Detect, and SD/HD.







T_{ACQ} = Acquisition Time, defined in the AC Electrical Characteristics Table

 T_1 = Time from Lock Detect assertion or deassertion until SD/ $\overline{\text{HD}}$ output is valid, typically 37 ns (one 27 MHz clock period)

 T_2 = Time from SDI input change until Lock Detect de-assertion, 1 ms maximum. SD/ \overline{HD} output is not valid during this time.

Figure 6. SDI, Lock Detect, and SD/HD Timing

SCO_EN

Input SCO_EN enables the SCO/SDO2 differential output to function either as a serial data-rate clock or second serial data output. SCO/SDO2 functions as a serial data-rate clock when SCO_EN is high. This pin has an internal pull-down device. The default state (low) enables the SCO/SDO2 output as a second serial data output.

CRYSTAL OR EXTERNAL CLOCK REFERENCE

The LMH0046 uses a 27 MHz crystal or external clock signal as a timing reference input. A 27 MHz parallel resonant crystal and load network may be connected to the XTAL IN/EXT CLK and XTAL OUT pins. Alternatively, a 27 MHz LVCMOS compatible clock signal may be input to XTAL IN/EXT CLK. Parameters for a suitable crystal are given in Table 4.



Table 4. Crystal Parameters

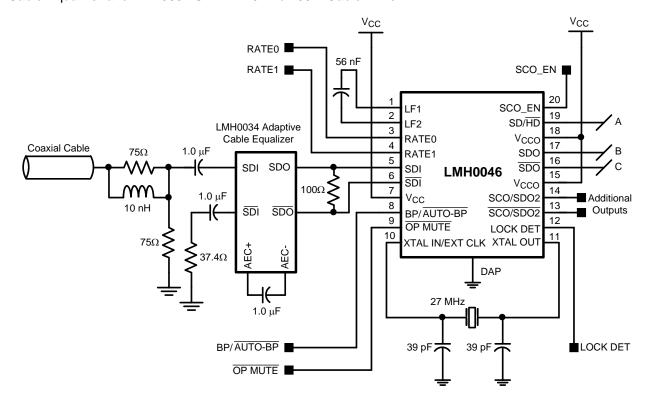
Parameter	Value
Frequency	27 MHz
Frequency Stability	±50 ppm @ recommended drive level
Operating Mode	Fundamental mode, Parallel Resonant
Load Capacitance	20 pF
Shunt Capacitance	7 pF
Series Resistance	40Ω max.
Recommended Drive Level	100 μW
Maximum Drive Level	500 μW
Operating Temperature Range	−10°C to +60°C

Product Folder Links: LMH0046



APPLICATION INFORMATION

Figure 7 shows an application circuit for the LMH0046 along with the LMH0034 SMPTE 292M / 259M Adaptive Cable Equalizer and LMH0002 SMPTE 292M / 259M Cable Driver.



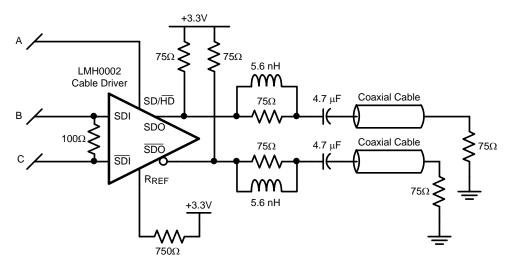


Figure 7. Application Circuit

SNLS222F - APRIL 2006-REVISED APRIL 2013



REVISION HISTORY

Cł	nanges from Revision E (April 2013) to Revision F	Pag	ge
•	Changed layout of National Data Sheet to TI format	•	13



PACKAGE OPTION ADDENDUM

7-Oct-2013

PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LMH0046MH/NOPB	ACTIVE	HTSSOP	PWP	20	73	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	L046	Samples
LMH0046MHX/NOPB	ACTIVE	HTSSOP	PWP	20	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	L046	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMH0046MHX/NOPB	HTSSOP	PWP	20	2500	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMH0046MHX/NOPB	HTSSOP	PWP	20	2500	367.0	367.0	38.0



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